



VCx-940P6WA

940nm 6W Pulsed VCSEL Diode

Data Sheet

Features

- 940nm VCSEL diode
- Output power: 6000mW (ms pulse)
- High power stability vs. temperature
- Available in SMD or T-mount package options

Applications

- 3D sensors / Lidars
- IR illumination
- Medical applications
- Pump source

Ordering Information

Part Number	Description
VC50A-940P6WA	940nm 6W Pulsed VCSEL Diode, SMD 5050 Package
VCTMC-940P6WA	940nm 6W Pulsed VCSEL Diode, T-Mount Package

* Additional package configurations may be available upon request.

Absolute Maximum Ratings

Parameters	Symbol	Rating	Unit	Conditions
Operating Temperature	Top	-40 to 105	°C	
Junction Temperature	Tj	-40 to 125	°C	
Storage Temperature	Tstg	-40 to 125	°C	
Reflow Soldering Temperature	Tsol	260	°C	10 seconds
Reverse Voltage	Vr	5	V	
Maximum Continuous Current	I _{max}	9	A	
ESD Exposure (Human Body) Model	ESD	8-10K	V	Class 3
ESD Exposure (Machine) Model	ESD	800-1000	V	Class C
Moisture Sensitivity Level	MSL	2	-	

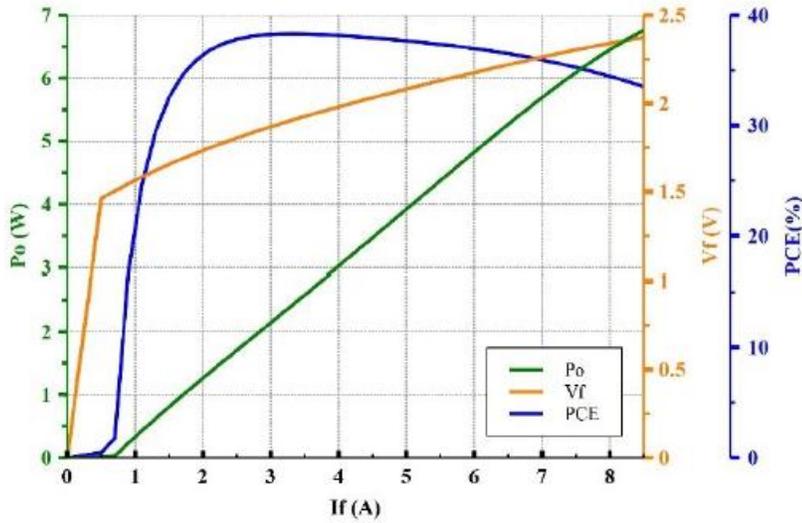
Electrical-Optical Characteristics (T_{op}=25°C)

Parameters	Symbol	Min.	Typ.	Max.	Unit	Conditions
Optical Output Power (0.1ms pulse width, 1% duty cycle)	P _o	-	6	-	W	I _F =7.3A
Optical Output Power (CW mode)	P _o	3	-	3.5	W	I _F =5A
Threshold Current	I _{th}	-	0.65	-	A	
Forward Current	I _F	-	7.3	-	A	
Slope Efficiency	η	-	0.9	-	W/A	P _o =6W
Power Conversion Efficiency	PCE	-	36	40	%	I _F =7.3A
Peak Wavelength	λ _P	930	940	950	nm	I _F =7.3A
Laser Forward Voltage	V _F	-	2.28	-	V	I _F =7.3A
Differential Resistance	R	-	0.1	-	Ω	I _F =7.3A
Beam Divergence	(1/e ²)	θ	-	20	-	deg
	FWHM	θ	-	16	-	deg
Wavelength Temperature Drift	Δλ _P /ΔT	-	-	0.07	nm/°C	I _F =7.3A
Emission Area			822x791		um ²	
Number of Emission Aperture			598			
Soldering Temperature				260	°C	10 seconds

Note: Electro-optical characteristics with a package or diffuser would require further evaluation. Values are based on limited sample size and estimated values.

Typical Characteristics

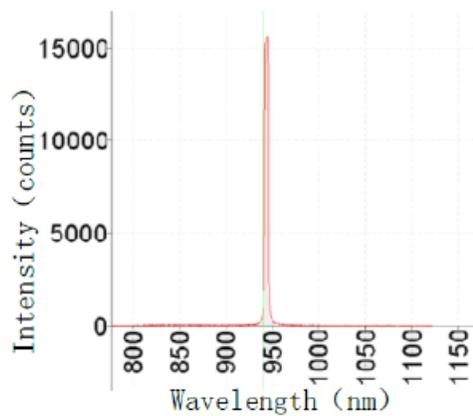
LIV Graph



Notes:

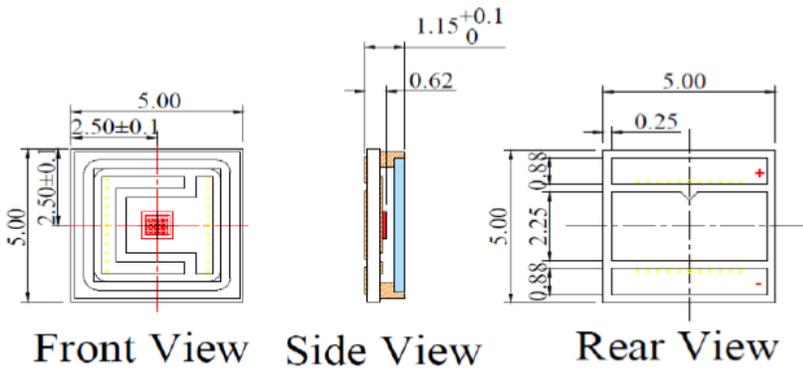
1. LIV graph was measured at 25°C (left); power output, voltage and power conversion efficiency variation trend with changed operating temperature (right, normalized).
2. Forward Voltage (V_F) measurement allowance is ±0.1V.
3. Peak Wavelength (λ_P) measurement allowance is ±1.5nm.
4. Others measurement allowance is ±10%.

Intensity vs. Wavelength

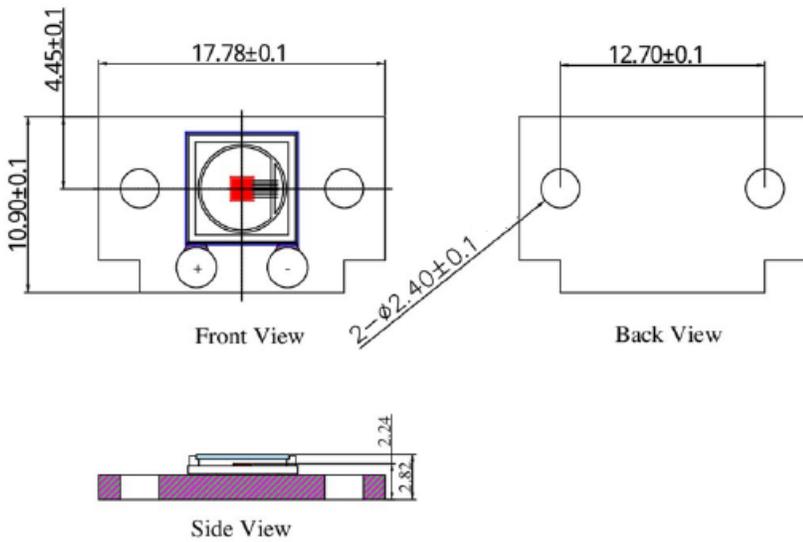


Outline Dimensions (unit: mm)

SMD 5050 Package



T-Mount Package



SMT Reflow Soldering Curve



Note: Reflow soldering can be operated only one time. During the temperature ramp-up, no forces may be exerted on the LD which would deform or damage them. After soldering is completed, please do not process until the product temperature ramps down to room temperature.

Additional Notes

1. Stresses exceeding those listed in Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress limits only and do not imply functional operation under such conditions. Exposure to conditions beyond recommended operating limits may affect device reliability.
2. Operation at or near maximum ratings may degrade performance and may create potential safety risks, including device failure.
3. The device is sensitive to electrostatic discharge (ESD). Proper ESD precautions, including grounded wrist straps, antistatic work surfaces, and ESD-safe handling procedures, must be followed during handling and assembly.
4. Adequate thermal management must be provided. The VCSEL device should be properly mounted to ensure efficient heat transfer to the package or system thermal path to maintain stable optical performance.
5. Avoid direct exposure of laser radiation to human eyes or skin. Follow applicable laser safety regulations and system-level safety design practices.
6. The emitting surface of the VCSEL should not be touched or contaminated. Mechanical contact or contamination may degrade optical performance or damage the device.
7. Use appropriate pick-and-place handling tools, such as ceramic or ESD-safe vacuum nozzles, to prevent mechanical or electrostatic damage during assembly.
8. Specifications are subject to change without notice.